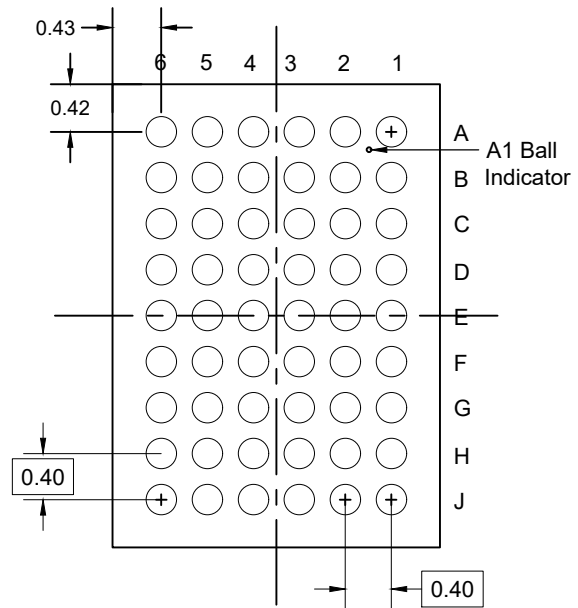
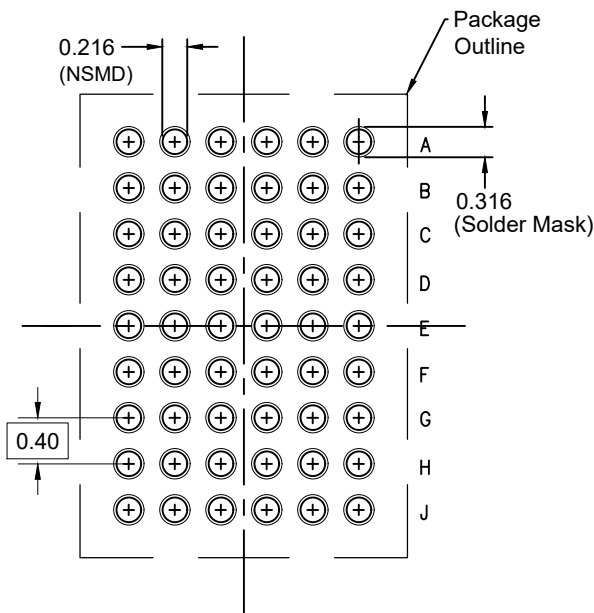


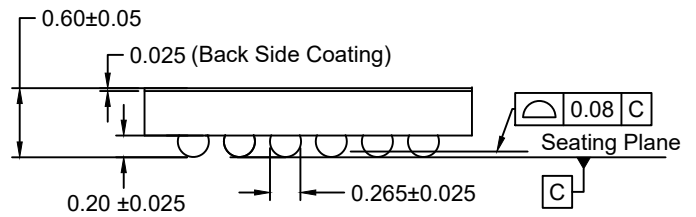
TOP VIEW



BOTTOM VIEW



Recommended Land Pattern
(PCB Top View, SMD Design)



SIDE VIEW

NOTES:

1. JEDEC compatible.
2. All dimensions are in mm and angles are in degrees.
3. Use ±0.05 mm tolerance for other dimensions.
4. Numbers in () are for reference only.
5. Pre-reflow solderball diameter is Ø0.25 mm.
6. UBM diameter is Ø0.24 mm.